

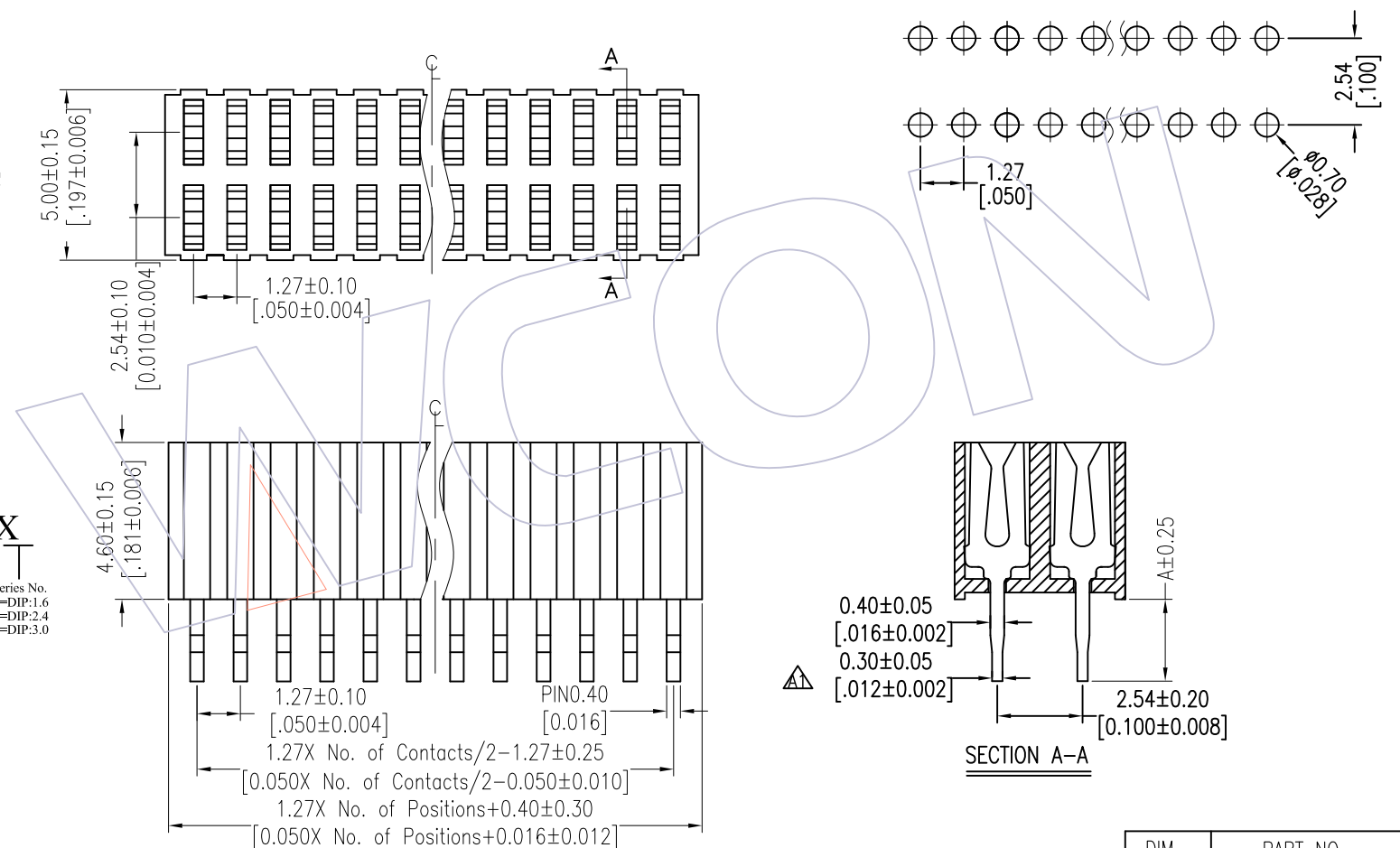
HSF

NOTES:

Current Rating: 1.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au over Ni
 Insulator Material: PA9T+30%GF UL94V-0

Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



Ordering Information

2446-2 XX S XX CYN T X

No. of Pins per Row: 02-50Pin

Contact Plating:
 G0=Gold Flash
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold

Packing:
 T=Tube

Series No.
 1=DIP:1.6
 2=DIP:2.4
 3=DIP:3.0

Item	Pitch	Mating
Standard	1.27	1417/1425
Alternate		

DIM	PART NO.
A=1.6	2446-2XXSXXCYNT1
A=2.4	2446-2XXSXXCYNT2
A=3.0	2446-2XXSXXCYNT3

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW Wang	DATE 2013/11/11	SCALE UNIT	FIT mm	PART NO. SEE TABLE
				X.X	±0.40					
A1	2013/11/11	ADD DIM:0.30	-----	X.XX	±0.25	CHECK	DATE	SIZE	A4	TITLE: FH1.27x2.54mm DUAL Row 180° DIP H=4.60
A0	2012/07/10	NEW	-----	X.XXX	±0.15	APPROVE	DATE	SHEET	1/1	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL	APPROVE	DATE	PROJ.	Customer NO.	